

L Number	Hits	Search Text	DB	Time stamp
1	39	(KCN with (clean\$3 or rins\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 09:01
2	63	(KCN with (etch\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 09:02
3	45	(KCN with (etch\$3)) and (copper or nickel or ni or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 09:18
4	39	(KCN with (etch\$3)) and (copper or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 10:55
5	26	(KCN with ("20%"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 09:19
6	149	(216/14).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 10:49
7	1124	(216/13).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 10:43
8	22	((216/13).CCLS.) and (cyanide or KCN)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 10:43
9	215	(216/16).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 10:50
10	433	(216/17).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 10:52
11	24	(216/21).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 10:59
12	562	(228/103).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 10:55
13	622	(228/119).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 10:55
14	949	(216/100).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 11:00

15	467	(216/105).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 11:01
16	35	((216/100).CCLS.) or ((216/105).CCLS.) and (cyanide or KCN)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 11:02
17	21	((216/100).CCLS.) or ((216/105).CCLS.) and (cyanide or KCN) and (Ni or Nickel)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 11:03
18	29	((216/100).CCLS.) or ((216/105).CCLS.) and (cyanide or KCN) and (Cu or copper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/29 11:03
-	191	((nickel and gold) adj layer).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/27 12:43
-	39	((nickel and gold) adj layer) and etch\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/27 12:43
-	792	((nickel and gold and copper) and etch\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/27 12:58
-	9	((nickel and gold and copper) and rework\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/27 12:48
-	212	((nickel and gold and copper) and etch\$3 and pad\$1).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/27 12:47
-	6	((nickel and gold and copper) and rework\$3).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/27 12:48
-	9	((bond\$3 adj pad\$1) and blasting).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/27 12:54
-	6	((bond\$3 adj pad\$1) and cyanide).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/27 12:50
-	14	((gold or nickel or copper) and pad\$1 and blasting).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/27 12:54
-	634	((nickel and gold and copper) and pad\$1).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/27 12:58

-	21	((bond\$3 adj pad\$1) and rework\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 08:43
-	43	((bond\$3 adj pad\$1) and rework\$3).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 07:24
-	40	((nickel and gold) adj layer\$1) and etch\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 11:47
-	98	((bond\$3 adj pad\$1) and rework\$3).clm.) or ((bond\$3 adj pad\$1) and rework\$3).ab.) or (((nickel and gold) adj layer\$1) and etch\$3).clm.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 07:43
-	14	("4007037") or ("4502924") or ("5489410") or ("5549809") or ("5682415") or ("5768339") or ("5858557")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 07:32
-	2	("6556030").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 07:34
-	21	("4931149" "5023697" "5024746" "5201454" "5225034" "5244140" "5354490" "5455195" "5527423" "5567300" "5785236" "5840629" "5863307" "5897375" "5948697" "5954997" "5958288" "6001730" "6027997" "6030425" "6340601").PN.	USPAT	2004/01/28 07:41
-	4	("5079070" "5449108" "6054659" "6211527").PN.	USPAT	2004/01/28 07:51
-	10	(bump and rework\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 07:52
-	63	((bond\$3 adj pad\$1) with rework\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 07:53
-	5	((bond\$3 adj pad\$1) with rework\$3) same etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 09:30
-	3	((connect\$3 adj site\$1) and rework\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 07:58
-	18	(bond\$3 adj pad\$1) same etch\$3 same blast\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 08:06
-	92	(bond\$3 adj pad\$1) and (etch\$3 same blast\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 08:12

-	17	(bond\$3 adj pad\$1) and (etch\$3 same cyanide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 08:14
-	88	(bond\$3 adj pad\$1) and (etch\$3 same pH)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 08:14
-	17	(bond\$3 adj pad\$1) and (etch\$3 same alkaline same pH)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 08:14
-	1	((copper adj pad\$1) and rework\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 08:43
-	1	((copper adj pad\$1) and blast\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 08:43
-	39	nickel same copper same etch\$3 same cyanide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 09:40
-	16	etchant\$1 with nickel with strip\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 10:02
-	1	etchant\$1 with nickel with pH with ("13" or "12" or "14")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 10:03
-	9	etchant\$1 with nickel with pH	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 10:05
-	6	((nickel with etchant) and ph).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 10:18
-	4	(nickel near3 etchant\$1) and (Ph adj2 ("12" or "13" or "14"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 10:25
-	64	diethyldithiocarbamate with ethylenediamine	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 11:47
-	3	diethyldithiocarbamate with ethylenediamine with (hydroxide or sulfonic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 11:49
-	28	enthone and ethylenediamine and nickel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 11:09

-	100	enthone.as. and nickel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 11:10
-	21	enthone.as. and nickel and strip\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 11:23
-	5	diethyldithiocarbamate same ethylenediamine same (hydroxide or sulfonic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 11:18
-	7	enthone.as. and nickel and strip\$3 and copper and steel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 11:55
-	3193	ethylenediamine with (hydroxide or sulfonic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 11:49
-	33	ethylenediamine with (hydroxide and sulfonic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 11:49
-	10	(ethylenediamine with (hydroxide and sulfonic)) and nickel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 11:49
-	9	enthone.as. and nickel and sulfonate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 11:55
-	16	((("4007037") or ("4502924") or ("5489410") or ("5549809") or ("5682415") or ("5768339") or ("5858557") or ("6083375"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 11:59
-	2	((("4007037") or ("4502924") or ("5489410") or ("5549809") or ("5682415") or ("5768339") or ("5858557") or ("6083375"))).PN.) and nickel and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 12:00
-	10	((("4007037") or ("4502924") or ("5489410") or ("5549809") or ("5682415") or ("5768339") or ("5858557") or ("6083375"))).PN.) and nickel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/28 12:00